

ABSTRACT OF THE DISCLOSURE

There are provided a recognition device, a wafer turning member, a turning device, and a control device. A first detection point for recognition and a second detection point for recognition are recognized, on the basis of the result of which a semiconductor wafer is turned to correct the inclination of ICs on the semiconductor wafer. As a result, the recognition operation for detecting the inclination of the ICs when a position of the ICs is to be recognized for bump formation is eliminated. The number of times the recognition is performed is reduced in comparison with the conventional art, so that the productivity can be improved.

5